



chip dimensions: 160 x 60 mils
substrate: 5 mil thick Alumina
metalization: WTi with 200u" Au for wire bonding
resistors: TaN, 50 Ohms/square
vias: 3 mil diameter, plated-thru
layers:

chip outline = cyan
top metal = black
backside metal = blue
vias = green
resistors = red

NATIONAL RADIO ASTRONOMY OBSERVATORY

1180 Boxwood Estate Rd, Charlottesville, VA, 22903

NAME: ksplit1

FILE: kspl11.dwg

DATE: 11/27/2007

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